

Sealing alloy

Specifications

| Item | C | S | P | Mn | Si | Ni | Cr | Co | Cu | Mo | Al | Fe |
|------|-------|-------|-------|-------|-------|-------------------|------|---------------|------|------|-------|-----|
| 4J29 | ≤0.03 | ≤0.02 | ≤0.02 | ≤0.50 | ≤0.30 | 28.5 ~ 29.5 | ≤0.2 | 16.8~ 17.8 | ≤0.2 | ≤0.2 | | Bal |
| 4J33 | ≤0.05 | ≤0.02 | ≤0.02 | ≤0.50 | ≤0.30 | 32.1 ~ 33.6 | | 14.0~ 15.2 | | | | Bal |
| 4J42 | ≤0.05 | ≤0.02 | ≤0.02 | ≤0.80 | ≤0.30 | 41.5 ~ 42.5 | | ≤0.1 | | | ≤0.10 | Bal |

Properties

4J22 and 4J29 alloys have a thermal expansion coefficient similar to glass and easily form compact oxide film necessary for the sealing.

Application

4J33 alloy has a thermal expansion coefficient similar to porcelain. It is used for vacuum electronic component.